

Antenna YC0011AA Datasheet

Antenna Services

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About the Document

Revision History

| Version | Date | Author | Note |
|---------|------------|-----------|--|
| - | 2020-09-22 | Kenny YIN | Creation of the document |
| 1.0 | 2020-09-22 | Kenny YIN | First official release |
| 1.1 | 2021-01-12 | Kenny YIN | Updated the antenna image in Chapter 2. |
| 1.2 | 2021-07-01 | Kenny YIN | Updated the package quantity in Chapter 8. |

Contents

| | | Document | | | |
|---|---|------------------------------------|--|--|--|
| 1 | Product Description5 | | | | |
| 2 | Produ | uct Features5 | | | |
| 3 | Produ | uct Specifications | | | |
| 4 | Overa | all Performance7 | | | |
| | 4.1. | Test Environment7 | | | |
| | 4.2. | Return Loss | | | |
| | 4.3. | Radiation Pattern9 | | | |
| | 4.4. | Reference PCB Design (Unit: mm)10 | | | |
| 5 | 5 Product Size (mm)11 | | | | |
| 6 | Relial | bility Test12 | | | |
| | 6.1. | Vibration Resist | | | |
| | 6.2. | Drop Shock | | | |
| | 6.3. | Resistance to Soldering Heat | | | |
| | 6.4. | Adhesive Strength of Termination12 | | | |
| | 6.5. | Bending Resist Test | | | |
| | 6.6. | Moisture Proof13 | | | |
| | 6.7. | High Temperature Endurance 13 | | | |
| | 6.8. | Low Temperature Endurance | | | |
| | 6.9. | Temperature Cycle Test | | | |
| 7 | 7 Reflow Soldering Standard Condition14 | | | | |
| 8 | Packa | aging and Dimensions14 | | | |
| | 8.1. | Plastic Tape | | | |
| | 8.2. | Reel (3000 pcs/reel) | | | |

1 Product Description

The antenna is designed for superior performance, and can be widely used for wireless applications.

We provide comprehensive antenna design support such as simulation, testing and manufacturing for custom antenna solutions to meet your specific application needs.

2 Product Features

- Wi-Fi/Bluetooth
- High efficiency
- Excellent performance



3 Product Specifications

| Passive Electrical Specifications | | | |
|-----------------------------------|------------------------------|--|--|
| Frequency Range | 2400–2500 MHz, 5150–5850 MHz | | |
| Input Impendence | 50 Ω | | |
| Return Loss | Max7 dB | | |
| Gain | ≤ 4 dBi | | |
| Polarization Type | Linear | | |
| Mechanical Specifications | | | |
| Antenna Size | 5.0 mm × 2.0 mm × 1.0 mm | | |
| Casing | - | | |
| Radiator | Ceramic Patch | | |
| Connector Type | SMD | | |
| Working Temperature | -40 °C to +85 °C | | |
| Radome Color | - | | |

4 Overall Performance

4.1. Test Environment

- KEYSIGHT VNA Network Analyzer E5063A, 100 kHz 6.5 GHz
- RayZone[®] 2800 Chamber 5G (FR1) SISO/MIMO, 400 MHz 6.0 GHz



4.2. Return Loss

| ▶ [r1 S33 Smith (R+jX) Scale 1.000U [F1 D&M] | |
|---|--------------------|
| 1 2.4180180 GHz 18.692 Ω -4.8079-Ω 13,690 2 2.5180180 GHz 53.638 Ω -49.985 Ω 1.2877 3 2.450000 GHz 40.701 Ω 5.4617 Ω 387.28 4 5.1500000 GHz 21.918 Ω 10.386.2 282.57 >6 5.5000000 GHz 35.883 Ω -9.6158 Ω 3.0093 | pF pH fF |
| | |
| Tr2 S33 Log Mag 10.00dB/ Ref 0.000dB [F1] | |
| 50.00 1 2.4180180 GHz -6.7457 dB 40.00 2 2.5180180 GHz -7.3448 dB | |
| 3 2.4500000 GHz -18.307 dB | |
| 30.00 4 5.1500000 GHz -8.8999 dB 5 5.8500000 GHz -7.7011 dB | |
| 20.00 >6 5.5000000 GHz -14.082 dB | |
| 10.00 | |
| 0.000 | |
| -10.00 | 2 2 A |
| -20.00 | 4 - 5 V |
| -30.00 | |
| -40.00 | |
| -50.00 | |
| -50.00 | |

| Frequency (MHz) | 2418 | 2518 | 2450 | 5150 | 5850 | 5500 |
|-----------------|-------|-------|-------|-------|-------|-------|
| Return Loss | -6.75 | -7.34 | -18.3 | -8.90 | -7.70 | -14.1 |

4.3. Radiation Pattern





| XY Plane (+ Z View) | XZ Plane (- Y View) | XZ Plane (+ Y View) | XY Plane (+ Z View) | XZ Plane (- Y View) | XZ Plane (+ Y View) |
|-----------------------|-----------------------|-----------------------|-----------------------|---|-----------------------|
| x | X | x | x | x | x |
| | И | Z | | | z |
| XY Plane (- Z View) | YZ Plane (+ X View) | YZ Plane (- X View) | XY Plane (- Z View) | YZ Plane (+ X View) | YZ Plane (- X View) |
| × | N | Y LI | | Y I I I I I I I I | KI V |

4.4. Reference PCB Design (Unit: mm)



50 ohms feeding line T type matching circuit

5 Product Size (mm)



| Symbol | L | W | Т | а | b | С |
|------------|------------|-----------|----------|----------|----------|----------|
| Dimensions | 5.00 ±0.20 | 2.0 ±0.20 | 1.0 ±0.2 | 0.8 ±0.1 | 2.0 ±0.2 | 0.6 ±0.2 |

6 Reliability Test

| Temperature Range | 25 ±5 °C |
|-----------------------------|------------------|
| Relative Humidity Range | 55–75 % |
| Operating Temperature Range | -40 °C to +85 °C |
| Storage Temperature Range | -40 °C to +85 °C |

6.1. Vibration Resistance

The device should fulfil the electrical specification after being applied to the vibration of 10–55 Hz with amplitude of 1.5 mm for 2 hours in X, Y and Z directions respectively.

6.2. Drop and Shock Tests

The device should have no mechanical damage after dropping onto the hard wooden board from the height of 100 cm for 3 times at each facet of the 3 dimensions of the device.

6.3. Resistance to Soldering Heat

The device should have no damage after pre-heating at 120–150 °C for 120 seconds and immersion in Sn solder at 255 \pm 10 °C for 5 \pm 0.5 seconds, or electric iron at 300 \pm 10 °C for 3 \pm 0.5 seconds.

6.4. Adhesive Strength of Termination

The device should have no remarkable damage or removal of the termination after horizontal force of 5 N (\leq 0603); 10 N (> 0603) for 10 ±1 seconds.

6.5. Bending Resistance Test



Weld the product to the central part of the PCB with the thickness 1.6 ± 0.2 mm or 0.8 ± 0.1 mm as the illustration shows, and keep exerting force arrow-ward on it at speed of 1 mm/s, and hold for 5 ± 1 seconds at the position of 1.5 mm bending distance, so far, any peeling-off of the product metal coating should not be detected.

6.6. Moisture Proof

The device should fulfil the electrical specification after being exposed to the temperature 60 \pm 2 °C and the relative humidity 90–95 % for 96 hours and experiencing 1–2 hours recovery time under normal condition.

6.7. High Temperature Endurance

The device should fulfil the electrical specification after being exposed to temperature 85 \pm 5 °C for 96 \pm 2 hours and experiencing 1–2 hours recovery time under normal temperature.

6.8. Low Temperature Endurance

The device should fulfil the electrical specification after being exposed to the temperature -40 \pm 5 °C for 96 \pm 2 hours and experiencing 2 hours recovery time under normal temperature.

6.9. Temperature Cycle Test

The device should fulfil the electrical specification after being exposed to the low temperature -40 °C and high temperature +85 °C for 30 ±2 minutes each by 5 cycles and experiencing 1 to 2 hours recovery time under normal temperature.



7 Reflow Soldering Standard Condition



8 Packaging and Dimensions

8.1. Plastic Tape



Packaging Note:

Reserve 150–200 mm of space at the trailing end of the carrier, 250–300 mm of space at the front end of the carrier and a further 250 mm space of cover tape at the front end of the carrier.

8.2. Reel (3000 pcs/reel)

